

Customer: Akros
 Package: 20L QLMP
 Device: AS1260

MATERIAL	WEIGHT (mg)	Components	CAS Number	Composition %	Weight/Device (mg)	% wt	ppm
Adhesive Sumitomo CRM1076NS	0.8059	Silver	7440-22-4	80.00	0.644720	0.91822	9,182
		Epoxy Resins	9003-36-5	10.00	0.080590	0.11478	1,148
		Diluent	26447-14-3	6.00	0.048354	0.06887	689
		Dicyandiamide	461-58-5	0.50	0.004030	0.00574	57
		Hardner	620-92-8	3.50	0.028207	0.04017	402
Lead Frame QPL	26.7324	Copper	7440-50-8	97.09	25.953151	36.96288	369,629
		Iron	7439-89-6	2.30	0.614845	0.87567	8,757
		Lead	7439-92-1	0.01	0.001337	0.00190	19
		Silver	7440-22-4	0.40	0.106930	0.15229	1,523
		Phosporous	7723-14-0	0.09	0.024059	0.03427	343
		Zinc	7440-66-6	0.12	0.032079	0.04569	457
Plating 100% matt tin	2.6321	Tin	07440-31-5	99.99	2.631837	3.74830	37,483
		Lead	07439-92-1	0.005	0.000132	0.00019	2
		Copper	07440-50-8	0.003	0.000079	0.00011	1
		Antimony	07440-36-0	0.001	0.000026	0.00004	0
Gold wire	0.6496	Gold	7440-57-5	100.00	0.649600	0.92517	9,252
Encapsulation Sumitomo G770HCD	35.8757	Silica Fused	60676-86-0	89.70	32.180503	45.83197	458,320
		Epoxy Resin	Trade secret	5.00	1.793785	2.55474	25,547
		Phenol Resin	Trade secret	5.00	1.793785	2.55474	25,547
		Carbon Black	1333-86-4	0.30	0.107627	0.15328	1,533
Silicon Chip	3.5184	Si (Die)	7440-21-3	100.00	3.518400	5.01096	50,110
Total weight (mg)	70.2141					100.00	1,000,000